

Small Signal Schottky diode

RB520S-30C2

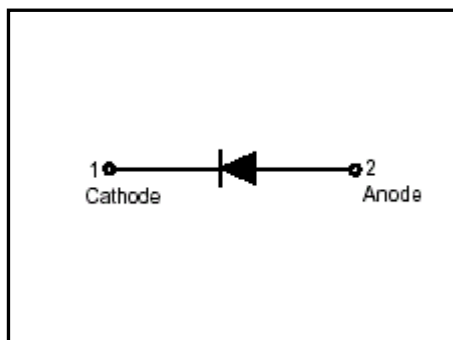
Description

These devices are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely small surface mounting type.(SC-79/SOD523)
- Extremely fast switching speed
- Low reverse current
- Extremely low forward voltage.($V_F=0.6V$ max. at 200mA)

Symbol



Outline



Absolute Maximum Ratings

- Maximum Temperatures

Storage Temperature	T_{stg}	-55~+150°C
Junction Temperature	T_j	+150°C
- Maximum Voltages and Currents ($T_a=25^\circ C$)

DC Reverse Voltage	V_R	30 V
Mean Rectifying Current	I_F	200 mA
- Thermal Characteristics

Total Device Dissipation @ $T_A=25^\circ C$ (Note)	P_D	200mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	625°C/W

Note: FR-5 board minimum pad.

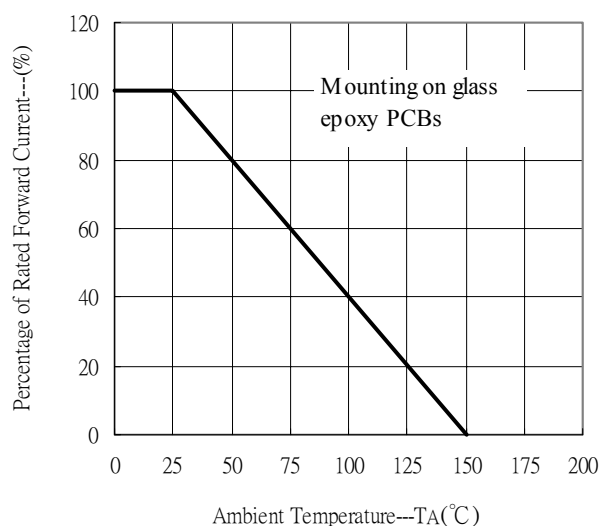


Characteristics (Ta=25°C)

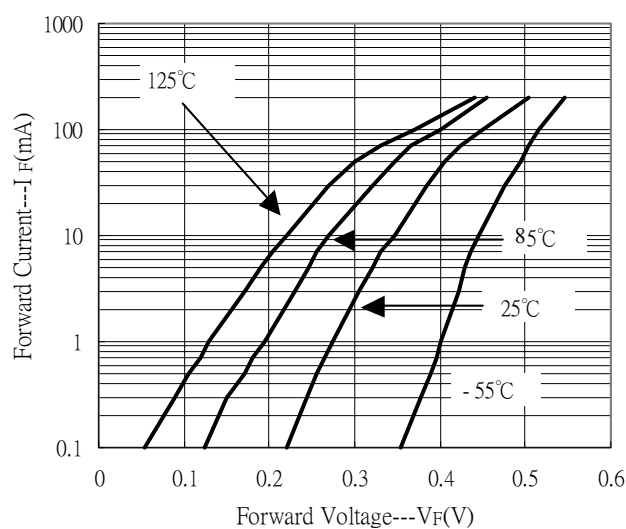
Characteristic	Symbol	Condition	Min.	Max.	Unit
Forward Voltage	V _F	I _F =200mA	-	600	mV
Reverse Leakage Current	I _R	V _R =10V	-	1	μA

Characteristic Curves

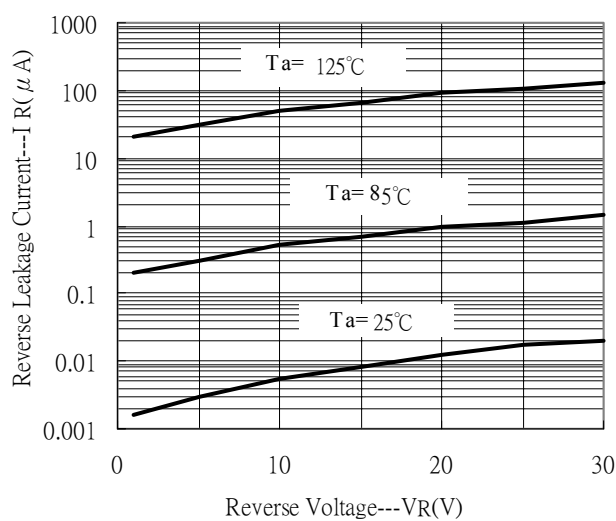
Forward Current Derating Curve



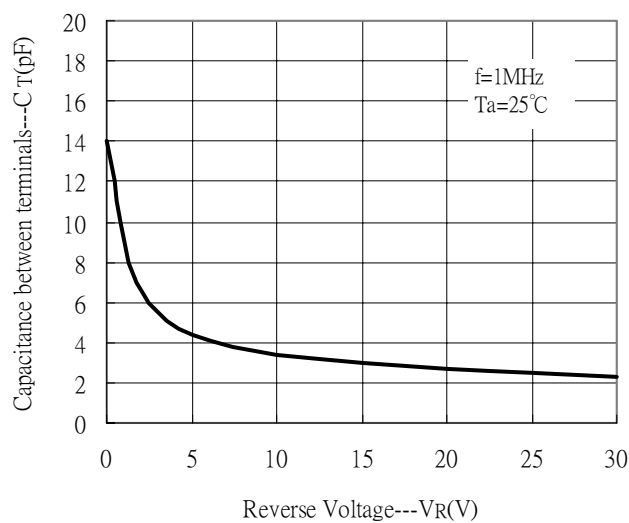
Forward Current vs Forward Voltage



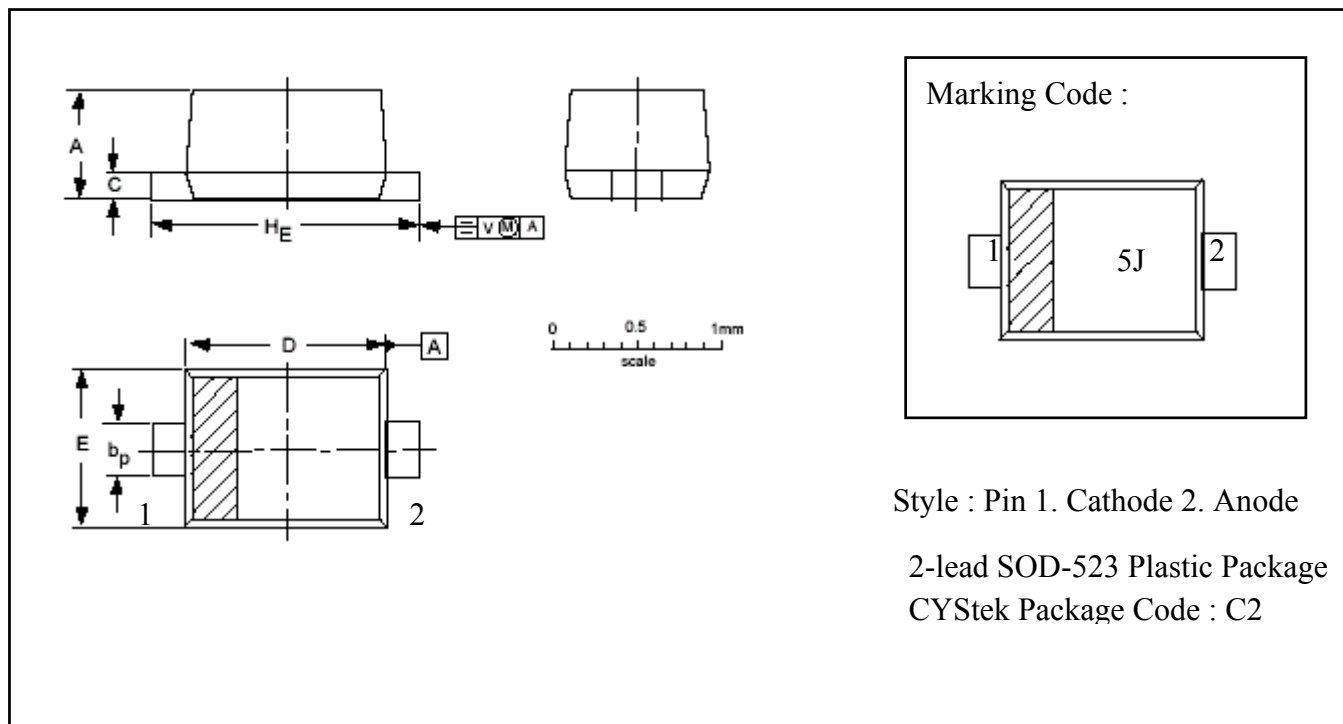
Reverse Leakage Current vs Reverse Voltage



Capacitance vs Reverse Voltage



SOD-523 Dimension



*: Typical

DIM	Millimeters		DIM	Millimeters	
	Min	.Max.		Min.	Max.
A	0.5	0.7	E	0.7	0.9
b _p	0.25	0.35	H _E	1.5	1.7
c	0.1	0.2	V	0.15(typ)	
D	1.1	1.3			

Notes: 1.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
2.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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